



US010267845B2

(12) **United States Patent**  
**Storey et al.**

(10) **Patent No.:** **US 10,267,845 B2**  
(45) **Date of Patent:** **Apr. 23, 2019**

- (54) **WAFER LEVEL BURN-IN SYSTEM**
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- (\* ) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 0 days.

- (21) Appl. No.: **15/593,601**
- (22) Filed: **May 12, 2017**

- (65) **Prior Publication Data**
- US 2018/0328978 A1 Nov. 15, 2018

- (51) **Int. Cl.**
- G01R 31/26** (2014.01)
- H01L 21/66** (2006.01)
- G01R 31/28** (2006.01)
- (52) **U.S. Cl.**
- CPC ..... **G01R 31/2642** (2013.01); **G01R 31/2875** (2013.01); **H01L 22/14** (2013.01)

- (58) **Field of Classification Search**
- None
- See application file for complete search history.

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**ABSTRACT**

(57) **ABSTRACT**

A system for simultaneously burning in, testing and curing all the die on an uncut semiconductor wafer having top and bottom surfaces, the system having upper and lower platen assemblies with a flow section configured to receive and discharge a temperature-controlled, circulated liquid heat transfer medium to maintain the temperatures of the top and bottom surfaces of the uncut semiconductor wafer within desired limits during wafer burn-in and testing and a programmable CPU and service controller configurable to selectively energize, monitor, test, display and store a plurality of performance parameters for the electronic circuitry of each of the plurality of die of the uncut semiconductor wafer simultaneously throughout a desired burn-in and test period.

**5 Claims, 16 Drawing Sheets**

